

## DESCRIPTION

The LT1187M/883 is a difference amplifier optimized for operation on  $\pm 5V$ , or a single 5V supply, and gain  $\geq 2$ . This versatile amplifier features uncommitted high input impedance (+) and (-) inputs, and can be used in differential or single-ended configurations. Additionally, a second set of inputs give gain adjustment and DC control to the difference amplifier.

The LT1187M/883's high slew rate,  $165V/\mu s$ , wide bandwidth, 50MHz, and  $\pm 20mA$  output current require only 13mA of supply current. The shutdown feature reduces the power dissipation to a mere 15mW, and allows multiple amplifiers to drive the same cable.

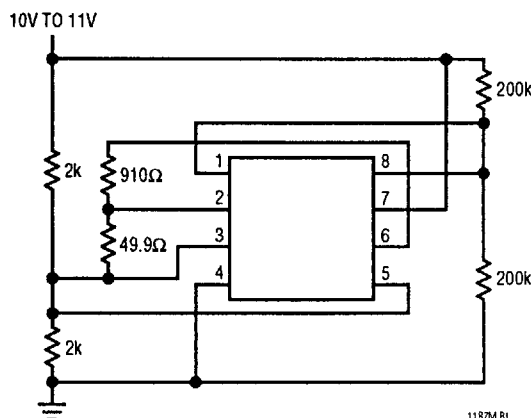
The LT1187M/883 is a low power version of the popular LT1193. For applications with gains of 10 or more, see the LT1189 data sheet.

The device is processed to the requirements of MIL-STD-883 Class B to yield circuits usable in precision military applications.

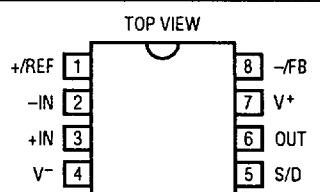
## ABSOLUTE MAXIMUM RATINGS

Total Supply Voltage ( $V^+$ to $V^-$ ) .....	18V
Differential Input Voltage .....	$\pm 6V$
Input Voltage .....	$\pm V_S$
Output Short Circuit Duration (Note 1) .....	Continuous
Operating Temperature Range .....	$-55^\circ C$ to $150^\circ C$
Junction Temperature (Note 2) .....	$175^\circ C$
Storage Temperature Range .....	$-65^\circ C$ to $150^\circ C$
Lead Temperature (Soldering, 10 sec) .....	$300^\circ C$

## BURN-IN CIRCUIT



## PACKAGE/ORDER INFORMATION

<p>TOP VIEW</p>  <p>J8 PACKAGE 8-LEAD HERMETIC DIP</p> <p><math>T_{JMAX} = 175^\circ C</math>, <math>\theta_{JA} = 100^\circ C/W</math></p>	ORDER PART NUMBER
	LT1187MJ8/883
	PART MARKINGS†
	LT1187MJ8/883C

† The suffix letter "C" of the part mark indicates compliance per MIL-STD-883, para 1.2.1.1.

**TABLE 1: ELECTRICAL CHARACTERISTICS**

$V_S = \pm 5V$ ,  $V_{REF} = 0V$ ,  $R_{FB1} = 900\Omega$  from pins 6 to 8,  $R_{FB2} = 100\Omega$  from pin 8 to ground,  $R_L = R_{FB1} + R_{FB2} = 1k$ ,  $C_L \leq 10pF$ , pin 5 open, unless otherwise noted. (Note 3)

SYMBOL	PARAMETER	CONDITIONS	NOTES	$T_A = 25^\circ C$		SUB-GROUP	$-55^\circ C \leq T_A \leq 125^\circ C$		SUB-GROUP	UNITS
				MIN	MAX		MIN	MAX		
$V_{OS}$	Input Offset Voltage	Either Input	4		10	1		15	2,3	mV
$I_{OS}$	Input Offset Current	Either Input			1.0	1		1.5	2,3	$\mu A$
$I_B$	Input Bias Current	Either Input			$\pm 2.0$	1		$\pm 3.5$	2,3	$\mu A$
CMRR	Common-Mode Rejection Ratio	$V_{CM} = -2.5V$ to $3.5V$		70		1	70		2,3	dB
PSRR	Power Supply Rejection Ratio	$V_S = \pm 2.375V$ to $\pm 8V$		70		1	60		2,3	dB
$V_{OUT}$	Output Voltage Swing	$V_S = \pm 5V$ , $R_L = 1k$ , $A_V = 50$ $V_S = \pm 8V$ , $R_L = 1k$ , $A_V = 50$ $V_S = \pm 8V$ , $R_L = 300\Omega$ , $A_V = 50$	3	$\pm 3.8$		4	$\pm 3.7$		5,6	V
				$\pm 6.7$		4	$\pm 6.6$		5,6	V
				$\pm 6.4$		4	$\pm 6.4$		5,6	V
$G_E$	Gain Error	$V_O = \pm 1V$ , $A_V = 10$ , $R_L = 1k$			1.0	4		1.0	5,6	%
SR	Slew Rate	$A_V = -1$ , $R_L = 1k$	6,10	100		7				$V/\mu s$
$t_r, t_f$	Rise Time, Fall Time	$A_V = 50$ , $V_{OUT} = \pm 1.5V$ , 20% to 80%	10	150	325	10				ns
$I_S$	Supply Current				16	1		17	2,3	mA
	Shutdown Supply Current	Pin 5 at $V^-$			1.5	1		1.5	2,3	mA
$I_{SD}$	Shutdown Pin Current	Pin 5 at $V^-$			25	1		25	2,3	$\mu A$

$V_S^+ = 5V$ ,  $V_S^- = 0V$ ,  $V_{REF} = 2.5V$ ,  $R_{FB1} = 900\Omega$  from pins 6 to 8,  $R_{FB2} = 100\Omega$  from pin 8 to  $V_{REF}$ ,  $R_L = R_{FB1} + R_{FB2} = 1k$ ,  $C_L \leq 10pF$ , pin 5 open, unless otherwise noted. (Note 3)

SYMBOL	PARAMETER	CONDITIONS	NOTES	$T_A = 25^\circ C$		SUB-GROUP	UNITS	
				MIN	MAX			
$V_{OS}$	Input Offset Voltage	Either Input	4		10	1	mV	
$I_{OS}$	Input Offset Current	Either Input			1.0	1	$\mu A$	
$I_B$	Input Bias Current	Either Input			$\pm 2.0$	1	$\mu A$	
CMRR	Common-Mode Rejection Ratio	$V_{CM} = 2V$ to $3.5V$		70		1	dB	
$V_{OUT}$	Output Voltage Swing	$R_L = 300\Omega$ to Ground $V_{OUT}$ High $V_{OUT}$ Low	3	3.6		4	V	
						0.4	4	V
$I_S$	Supply Current				15	1	mA	
	Shutdown Supply Current	Pin 5 at $V^-$			1.5	1	mA	
$I_{SD}$	Shutdown Pin Current	Pin 5 at $V^-$			25	1	$\mu A$	

## TABLE 1: ELECTRICAL CHARACTERISTICS

**Note 1:** A heat sink may be required to keep the junction temperature below absolute maximum when the output is shorted continuously.

**Note 2:**  $T_J$  is calculated from the ambient temperature  $T_A$  and power dissipation  $P_D$  according to the following formula:

$$T_J = T_A + (P_D \times 100^\circ\text{C/W})$$

**Note 3:** When  $R_L = 1k$  is specified, the load resistor is  $R_{FB1} + R_{FB2}$ , but when  $R_L = 300\Omega$  is specified, then an additional  $430\Omega$  is added to the output such that  $(R_{FB1} + R_{FB2})$  in parallel with  $430\Omega$  is  $R_L = 300\Omega$ .

**Note 4:**  $V_{OS}$  measured at the output (pin 6) is the contribution from both input pair, and is input referred.

**Note 5:**  $V_{IN\_LIM}$  is the maximum voltage between  $-V_{IN}$  and  $+V_{IN}$  (pin 2 and pin 3) for which the output can respond.

**Note 6:** Slew rate is measured between  $\pm 0.5V$  on the output, with a  $V_{IN}$  step of  $\pm 0.75V$ ,  $A_V = 3$  and  $R_L = 1k$ .

**Note 7:** Full power bandwidth is calculated from the slew rate measurement:  $FPBW = SR/2\pi V_p$ .

**Note 8:** Settling time measurement techniques are shown in "Take the Guesswork Out of Settling Time Measurements," *EDN*, September 19, 1985.

**Note 9:** NTSC (3.58MHz).

**Note 10:** AC parameters are 100% tested.

**Note 11:** See Application section in the standard data sheet for shutdown at elevated temperatures. Do not operate shutdown above  $T_J > 125^\circ\text{C}$ .

## TABLE 2: ELECTRICAL TEST REQUIREMENTS

MIL-STD-883 TEST REQUIREMENTS	SUBGROUP
Final Electrical Test Requirements (Method 5004)	1*,2,3,4,5,6,7,10
Group A Test Requirements (Method 5005)	1,2,3,4,5,6,7,10
Group C and D End Point Electrical Parameters (Method 5005)	1,2,3,4,5,6,7,10

\* PDA Applies to subgroup 1. See PDA Test Notes.

### PDA Test Notes

The PDA is specified as 5% based on failures from group A, subgroup 1, tests after cooldown as the final electrical test in accordance with method 5004 of MIL-STD-883 Class B. The verified failures of group A, subgroup 1, after burn-in divided by the total number of devices submitted for burn-in in that lot shall be used to determine the percent for the lot.

Linear Technology Corporation reserves the right to test to tighter limits than those given.